



Material Content Data Sheet



Halogen-Free

Sales Product Name	IRF100B201	Issued	21. July 2021
MA#	MA005548183		
Package	PG-TO220-3-904	Weight*	2363.08 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.902	0.21	0.21	2074	2074
leadframe	inorganic material	phosphorus	7723-14-0	0.499	0.02		211	
	non noble metal	iron	7439-89-6	1.664	0.07		704	
	non noble metal	copper	7440-50-8	1,661.709	70.31	70.40	703197	704112
wire	non noble metal	aluminium	7429-90-5	12.669	0.54	0.54	5361	5361
encapsulation	organic material	carbon black	1333-86-4	3.252	0.14		1376	
	plastics	epoxy resin	-	130.067	5.50		55042	
	inorganic material	silicondioxide	60676-86-0	517.018	21.88	27.52	218790	275208
leadfinish	non noble metal	tin	7440-31-5	25.685	1.09	1.09	10869	10869
solder	non noble metal	tin	7440-31-5	0.112			48	
	noble metal	silver	7440-22-4	0.140	0.01		59	
	non noble metal	lead	7439-92-1	5.361	0.23	0.24	2269	2376
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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